

SPECIFICATION Patent Pending

Part Number: PAD.71X.A

- Product Name: GEMINI EMBEDDED LTE MIMO 2*2 ANTENNA with PA.710.A and PA.711.A Antennas For 2G/3G/4G 2x2 MIMO systems applications LTE/GSM/CDMA/DCS/PCS/WCDMA/UMTS/HSPA/GPRS/EDGE/IMT 698MHz to 960MHz, 1710MHz to 2690Mhz
 - Features: Highest Efficiency Wide-band Embedded MIMO Antenna >40% on all 4G/3G/2G Bands
 - <0.3 ECC on all bands
 - Patent pending
 - SMA(F) Connectors
 - Surface Mount Technology
 - 120.0 x 125.0 x 0.75 mm

RoHS Compliant ✓





1. Introduction

The Gemini LTE MIMO 2*2 Embedded Antenna is the only compact MIMO antenna solution for the world LTE M2M and Internet of Things (IOT) market of today. Gemini has two antenna elements, the existing PA.710 LTE MIMO ceramic antenna successfully used in many LTE MIMO devices today, along with its new brother the PA.711 LTE MIMO ceramic antenna. By altering the radiation pattern of the PA.711 to that of the PA.710 (similar to reflecting), Taoglas has created the world's first high efficiency MIMO embedded wide-band cellular antenna conforming to an envelope correlation co-efficient of below 0.3. This minimal self interference is critical to achieve high data rates in today's advanced LTE systems.

The patent pending antenna is ideal for integration into high data throughput devices which depend on high efficiency MIMO antennas. Typical applications

- Intelligent Transport Systems
- High Definition Video Broadcast Systems
- Wireless LTE MIMO M2M devices with legacy 2G/3G Functionality

Antenna board size, dimensions and antenna placement have all been carefully evaluated for optimum performance. It is not recommended to go below this antenna board dimensions, as efficiency will reduce dramatically along with poor isolation. The antennas may also need to be re-tuned to fit into different custom enclosures. Taoglas offers full customization of the antenna system for your device.

Alternatively, PA.710 and PA.711 can be integrated directly on your main board, provided that you follow strict guidelines on meeting minimum main-board ground plane dimensions, transmission line design, matching, and placement of antennas.

Contact Taoglas regional sales office for support.



2. Specification

ELECTRICAL				
Antenna	PA.710 and PA.711			
Standard	4G/3G/2G			
Operation Frequency (MHz)	698~960MHz	1710~2170MHz	2300~2400MHz	2490~2690MHz
Peak Gain	1.0dBi	3.0dBi	3.5dBi	2.8dBi
Average Gain	-2.7 dB	-2.6 dB	-2.5dB	-2.2dB
Efficiency	53%	54%	55%	60%
VSWR	<3.5:1			
Impedance	50Ω			
Polarization	Linear			
Radiation Properties	Omni-directional			
Max Input Power	5 W			

• The PA.710 and PA.711 antennas performances were measured with 106x125mm ground plane.

MECHANICAL			
Dimensions (mm)	106x125.0x0.75 mm		
Material	FR4		
Termination	Ag (environmental-friendly Pb free)		
EVB Connector	SMA(F)		

ENVIRONMENTAL			
Operation Temperature	-40°C to 85°C		
Storage Temperature	-40°C to 105°C		
Relative Humidity	Non-condensing 65°C 95% RH		
RoHs Compliant Yes			



		LTE BANDS		
Band Number	LTE / LTE-Advanced / WCDMA / HSPA / HSPA+ / TD-SCDMA			
	Uplink	Downlink	PA710.A	PA.711.A
1	UL: 1920 to 1980	DL: 2110 to 2170	✓	√
2	UL: 1850 to 1910	DL: 1930 to 1990	✓	√
3	UL: 1710 to 1785	DL: 1805 to 1880	\checkmark	√
4	UL: 1710 to 1755	DL: 2110 to 2155	\checkmark	√
5	UL: 824 to 849	DL: 869 to 894	\checkmark	√
7	UL: 2500 to 2570	DL:2620 to 2690	\checkmark	\checkmark
8	UL: 880 to 915	DL: 925 to 960	\checkmark	\checkmark
9	UL: 1749.9 to 1784.9	DL: 1844.9 to 1879.9	\checkmark	\checkmark
11	UL: 1427.9 to 1447.9	DL: 1475.9 to 1495.9	×	×
12	UL: 699 to 716	DL: 729 to 746	\checkmark	\checkmark
13	UL: 777 to 787	DL: 746 to 756	\checkmark	\checkmark
14	UL: 788 to 798	DL: 758 to 768	\checkmark	\checkmark
17	UL: 704 to 716	DL: 734 to 746 (LTE only)	\checkmark	\checkmark
18	UL: 815 to 830	DL: 860 to 875 (LET only)	\checkmark	\checkmark
19	UL: 830 to 845	DL: 875 to 890	\checkmark	\checkmark
20	UL: 832 to 862	DL: 791 to 821	\checkmark	\checkmark
21	UL: 1447.9 to 1462.9	DL: 1495.9 to 1510.9	×	×
22	UL: 3410 to 3490	DL: 3510 to 3590	×	×
23	UL:2000 to 2020	DL: 2180 to 2200 (LTE only)	\checkmark	\checkmark
24	UL:1625.5 to 1660.5	DL: 1525 to 1559 (LTE only)	\checkmark	\checkmark
25	UL: 1850 to 1915	DL: 1930 to 1995	\checkmark	\checkmark
26	UL: 814 to 849	DL: 859 to 894	\checkmark	\checkmark
27	UL: 807 to 824	DL: 852 to 869 (LTE only)	\checkmark	\checkmark
28	UL: 703 to 748	DL: 758 to 803 (LTE only)	\checkmark	\checkmark
29	UL: -	DL: 717 to 728 (LTE only)	\checkmark	\checkmark
30	UL: 2305 to 2315	DL: 2350 to 2360 (LTE only)	✓	✓
31	UL: 452.5 to 457.5	DL: 462.5 to 467.5 (LTE only)	×	×
32	UL: -	DL: 1452 - 1496	\checkmark	\checkmark
35	1850 to 1910		\checkmark	\checkmark
38	2570 to 2620		\checkmark	✓
39	1880 to 1920		\checkmark	\checkmark
40	2300 to 2400		\checkmark	✓
41	2496 to 2690		√	\checkmark
42	3400 to 3600		×	×
43	3600 to 3800		×	×



3. Test Setup

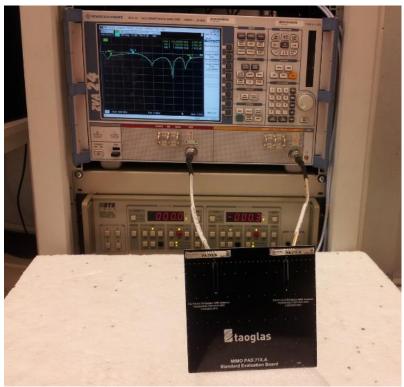


Figure 1. Return Loss and VSWR test set up

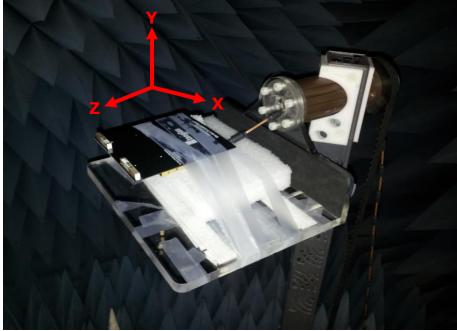
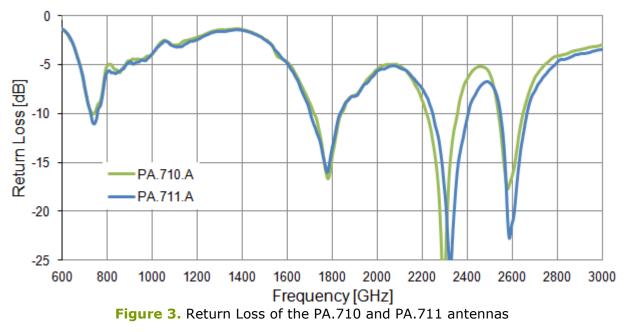


Figure 2. OTA test set up

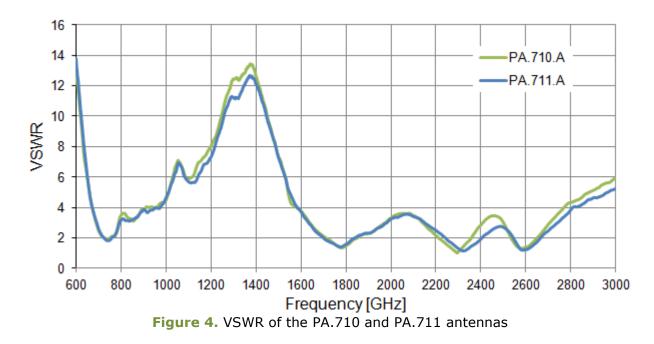


4. Antenna Parameters

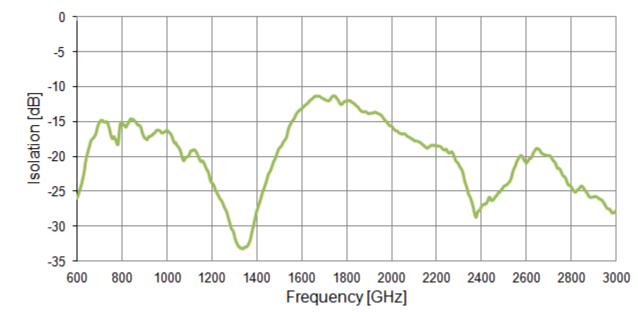
4.1. Return Loss



4.2. **VSWR**







4.3. Isolation



4.4. Envelope Correlation Coefficient

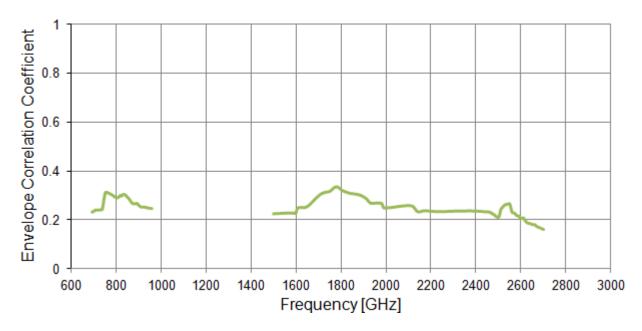
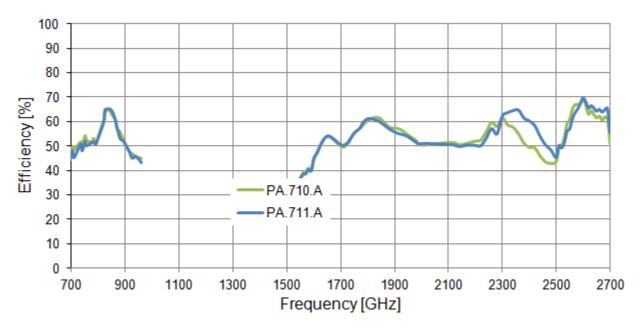
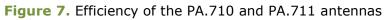


Figure 6. ECC of the PA.710 and PA.711 antennas



4.5. Efficiency





4.6. Peak Gain

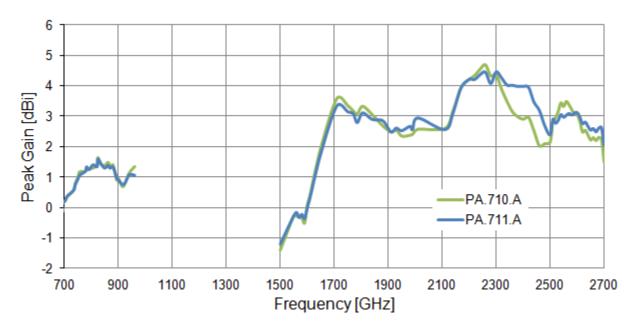


Figure 8. Peak Gain of the PA.710 and PA.711 antennas



4.7. Average Gain

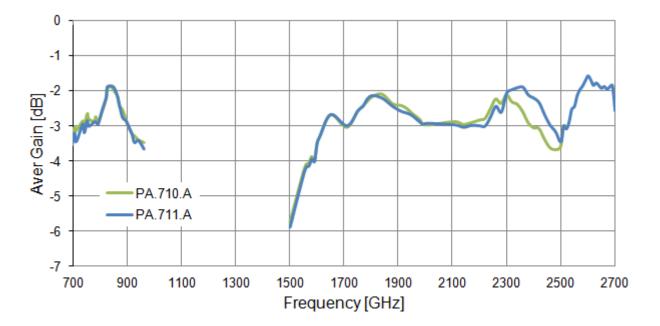
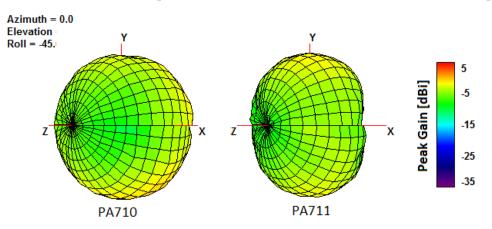
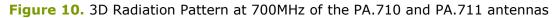


Figure 9. Average Gain of the PA.710 and PA.711 antennas



4.8. 3D Radiation Pattern (measured on 120*125mm EVB)





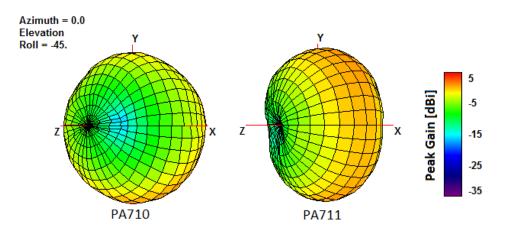
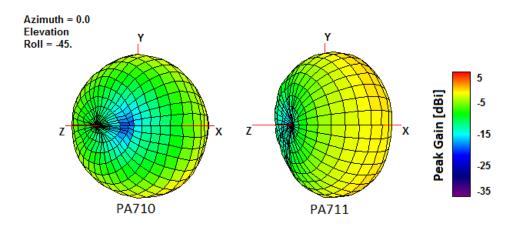
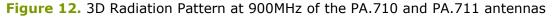


Figure 11. 3D Radiation Pattern at 800MHz of the PA.710 and PA.711 antennas







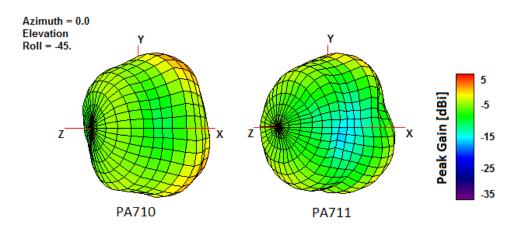


Figure 13. 3D Radiation Pattern at 1710MHz of the PA.710 and PA.711 antennas

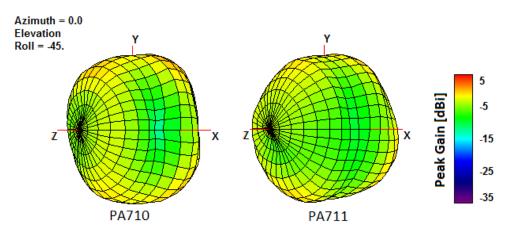


Figure 14. 3D Radiation Pattern at 1805MHz of the PA.710 and PA.711 antennas

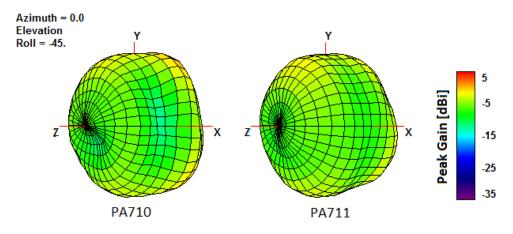


Figure 15. 3D Radiation Pattern at 1910MHz of the PA.710 and PA.711 antennas



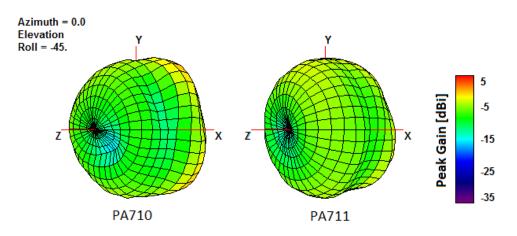


Figure 16. 3D Radiation Pattern at 1990MHz of the PA.710 and PA.711 antennas

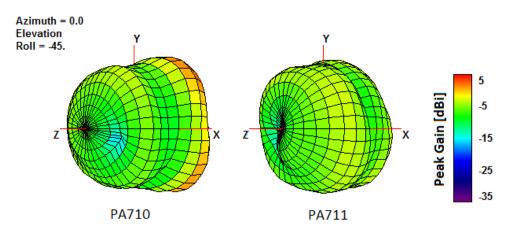


Figure 17. 3D Radiation Pattern at 2170MHz of the PA.710 and PA.711 antennas

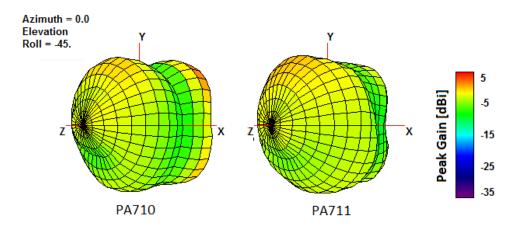


Figure 18. 3D Radiation Pattern at 2400MHz of the PA.710 and PA.711 antennas



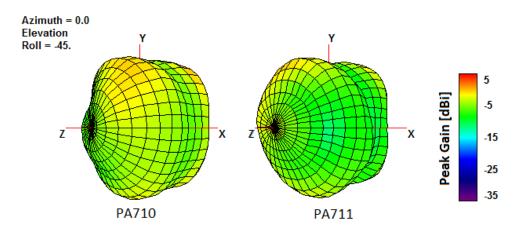


Figure 19. 3D Radiation Pattern at 2500MHz of the PA.710 and PA.711 antennas

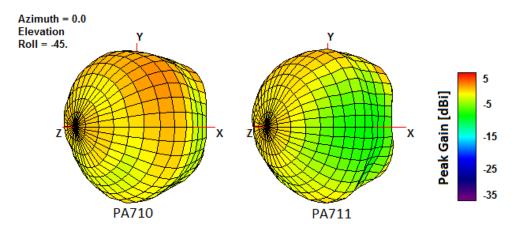


Figure 20. 3D Radiation Pattern at 2600MHz of the PA.710 and PA.711 antennas

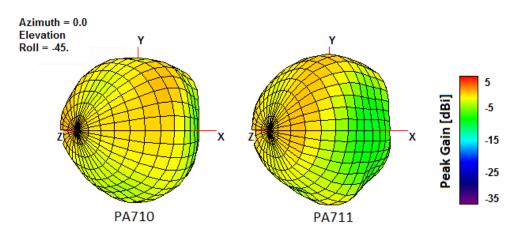


Figure 21. 3D Radiation Pattern at 2700MHz of the PA.710 and PA.711 antennas



4.9. PA.710 2D Radiation Pattern (measured on 120*125mm EVB)

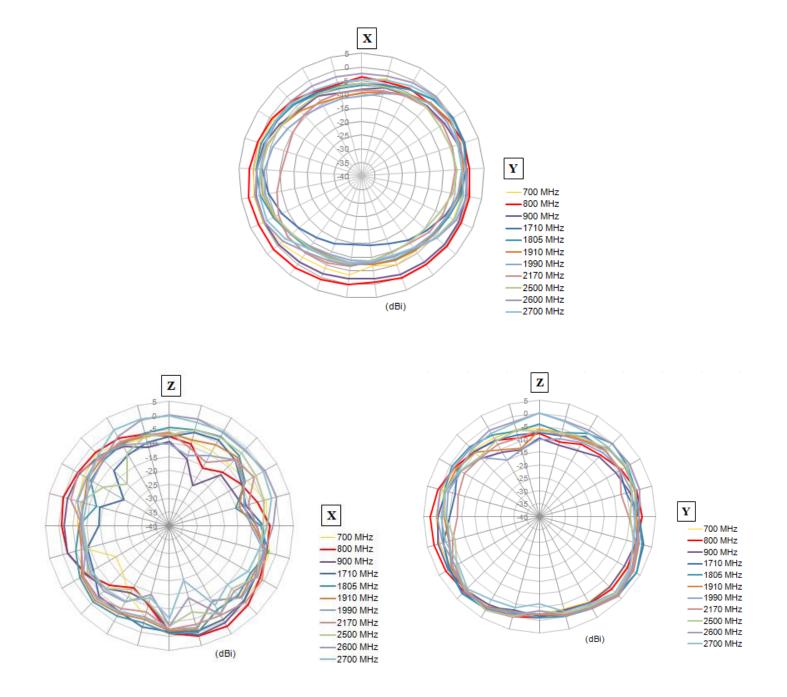


Figure 22. 2D Radiation Pattern of the PA.710 Antenna



4.10. PA.711 2D Radiation Pattern (measured on 120*45mm EVB)

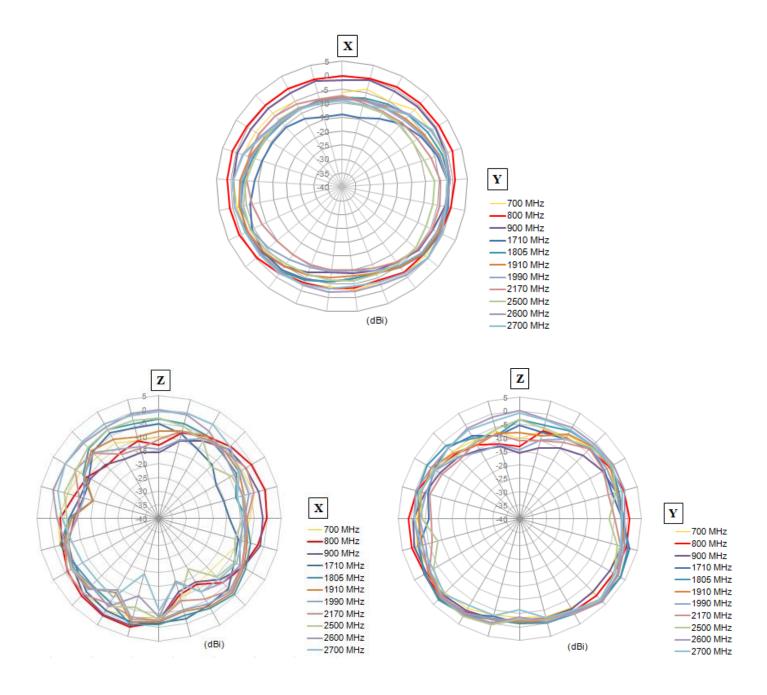
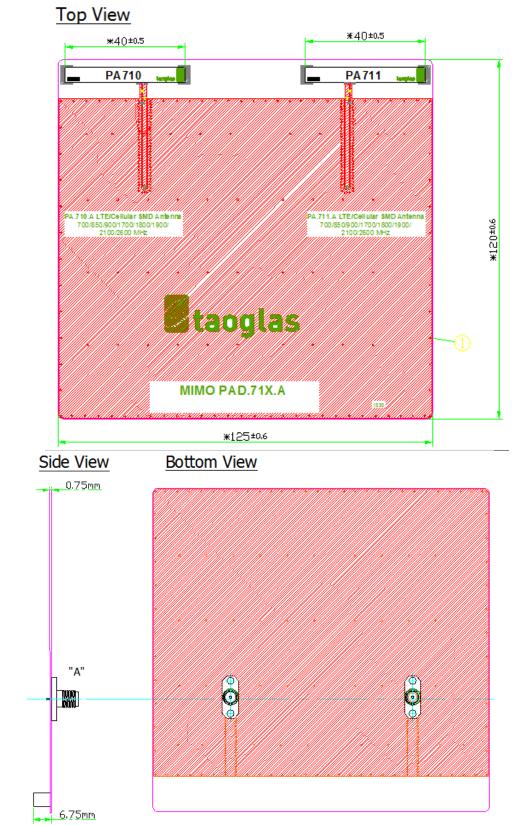


Figure 23. 2D Radiation Pattern of the PA.711 Antenna

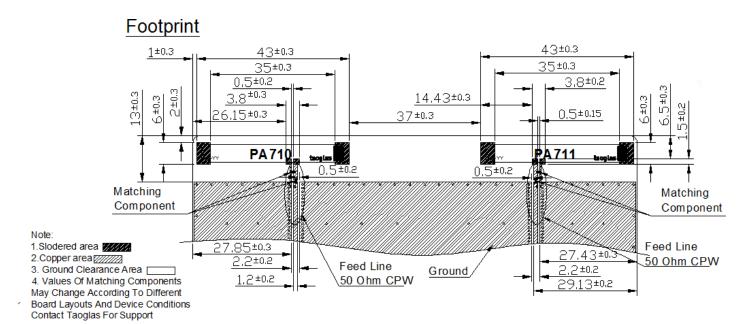




5. Mechanical Drawing (Unit: mm)

Figure 24. Mechanical drawing of PAD.71X.A

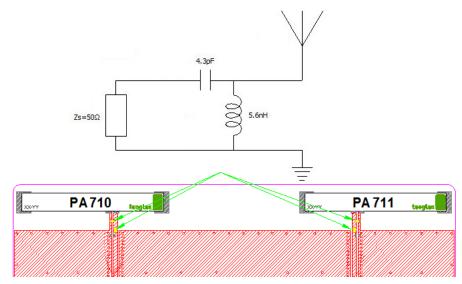




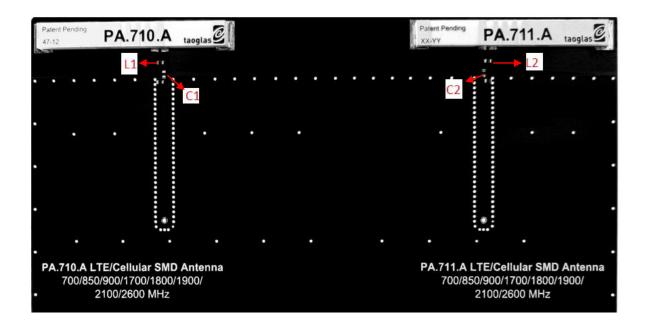
6. Layout Dimensions (Unit: mm)



7. Matching Circuit





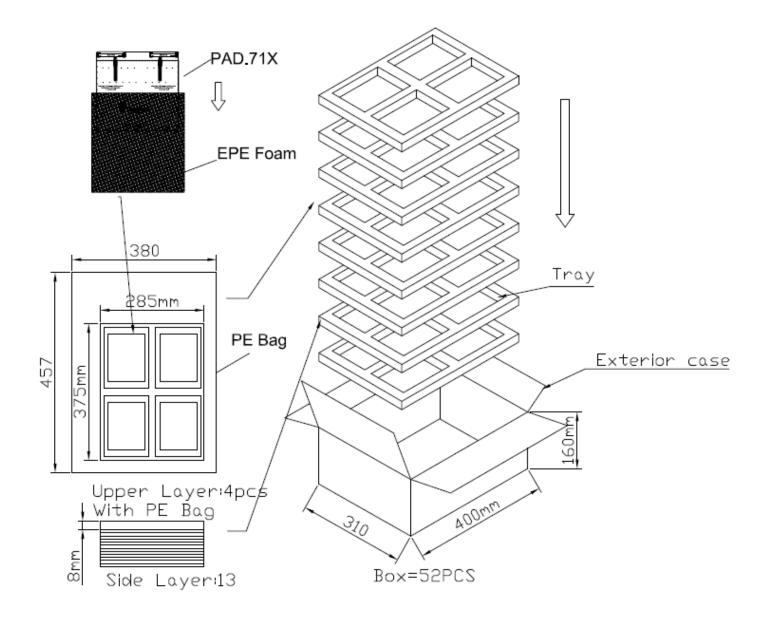


Circuit Symbol	Size	Description
L1	0402	5.6nH inductor (LQG15HS5N6S02D)
C1	0402	4.3pF Capacitor (GRM1555C1H4R3CA01D)
L2	0402	5.6nH inductor (LQG15HS5N6S02D)
C2	0402	4.3pF Capacitor (GRM1555C1H4R3CA01D)

Figure 26. Recommended matching circuit



8. Packaging





9. Recommended Reflow Temperature Profile

PA.710 and the PA.711 can be assembled following either Sn-Pb or Pb-Free assembly processes. The recommended soldering temperatures are as follows:

Phase	Profile Features	Sn-Pb Assembly	Pb-Free Assembly (SnAgCu)
Ramp-Up	Avg. Ramp-Up Rate (Tsmax to TP)	3°C/second (max)	3°C/second (max)
Preheat	Temperature Min (Tsmin)	100°	100°
	Temperature Max (Tsmax)	150°	150°
	Time (tsmin to tsmax)	60-120 seconds	60-120 seconds
Reflow	Temperature (TL)	183°C	217°C
	Total Time Above T∟ b(t∟)	60-150 seconds	60-150 seconds
Peak	Temperature (Tp)	235°C	260°C
	Time (tp)	10-30 seconds	20-40 seconds
Ramp-Down	Rate	6°C/second (max)	6°C/second (max)
Time from 25°C	to peak Temperature	6 minutes max	8 minutes max

Temperature profile - (green area) for the assembly process in reflow ovens

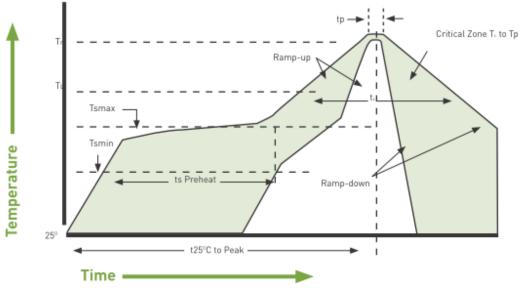


Figure 27. Temperature profile for the assembly process in reflow ovens